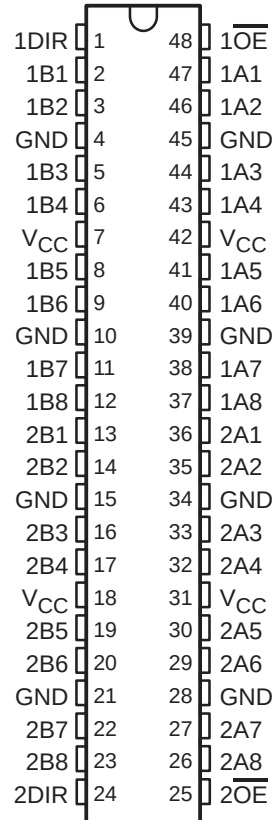


SN54ABTH16245, SN74ABTH16245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS662I – MARCH 1996 – REVISED MARCH 1999

- Members of the Texas Instruments *Widebus™* Family
- State-of-the-Art *EPIC-II B™* BiCMOS Design Significantly Reduces Power Dissipation
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- High-Impedance State During Power Up and Power Down
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

SN54ABTH16245 . . . WD PACKAGE
SN74ABTH16245 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The 'ABTH16245 devices are 16-bit noninverting 3-state transceivers that provide synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the devices so that the buses are effectively isolated.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54ABTH16245 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABTH16245 is characterized for operation from -40°C to 85°C .



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus and EPIC-II B are trademarks of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

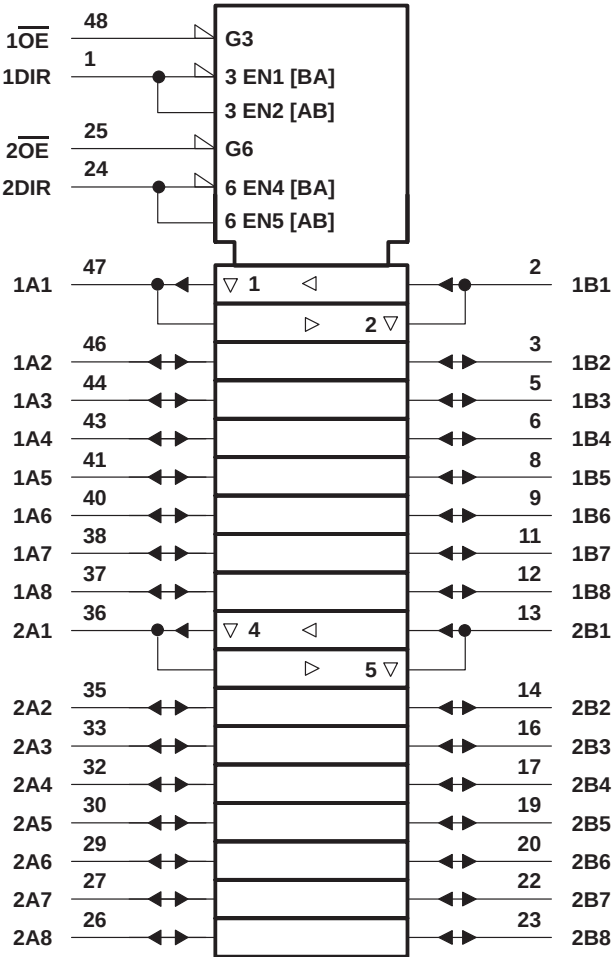
SN54ABTH16245, SN74ABTH16245
16-BIT BUS TRANSCEIVERS
WITH 3-STATE OUTPUTS

SCBS662I – MARCH 1996 – REVISED MARCH 1999

FUNCTION TABLE
(each 8-bit section)

INPUTS		OPERATION
OE	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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SN54ABTH16245, SN74ABTH16245

16-BIT BUS TRANSCEIVERS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T _A = 25°C			SN54ABTH16245		SN74ABTH16245		UNIT
			MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA				-1.2		-1.2		-1.2	V
V _{OH}	V _{CC} = 4.5 V, I _{OH} = -3 mA		2.5			2.5		2.5		V
	V _{CC} = 5 V, I _{OH} = -3 mA		3			3		3		
	V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				
		I _{OH} = -32 mA	2*					2		
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V
		I _{OL} = 64 mA			0.55*				0.55	
V _{hys}				100						mV
I _I	Control inputs	V _{CC} = 5.5 V, V _I = V _{CC} or GND			±1		±1		±1	μA
	A or B ports				±100		±100		±100	
I _I (hold)	V _{CC} = 4.5 V	V _I = 0.8 V	100			100		100		μA
		V _I = 2 V	-100			-100		-100		
I _{OZPU}	V _{CC} = 0 to 1.9 V	V _O = 0.5 V to 2.7 V, OE = X			±50**		±50**			μA
	V _{CC} = 0 to 2.1 V				±50				±50	
I _{OZPD}	V _{CC} = 1.9 V to 0	V _O = 0.5 V to 2.7 V, OE = X			±50**		±50**			μA
	V _{CC} = 2.1 V to 0				±50				±50	
I _{off}	V _{CC} = 0, V _I or V _O ≤ 4.5 V				±100				±100	μA
I _{CEX}	V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μA
I _O [‡]	V _{CC} = 5.5 V, V _O = 2.5 V		-50	-100	-180	-50	-180	-50	-180	mA
I _{CC}	A or B ports	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND			2		2		2	mA
		Outputs high			32		32		32	
		Outputs disabled			2		2		2	
ΔI _{CC} [§]	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1.5		1.5		1.5	mA
C _i	Control inputs	V _I = 2.5 V or 0.5 V			3					pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			6					pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All typical values are at V_{CC} = 5 V.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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SN54ABTH16245, SN74ABTH16245
16-BIT BUS TRANSCEIVERS
WITH 3-STATE OUTPUTS

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABTH16245					UNIT
			V _{CC} = 5 V, T _A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	1	2.2	3.6	0.5	4.1	ns
t _{PHL}			1	2.3	3.8	0.5	4.4	
t _{PZH}	$\overline{OE}$	B or A	1	3.6	5.2	0.8	6.4	ns
t _{PZL}			1	3.7	6.1	0.9	6.5	
t _{PHZ}	$\overline{OE}$	B or A	2	4.4	6.7	1.3	7.9	ns
t _{PLZ}			1.5	3.3	4.7	1.4	5.6	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABTH16245					UNIT
			V _{CC} = 5 V, T _A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	1	2.2	3.4	1	3.9	ns
t _{PHL}			1	2.3	3.7	1	4.2	
t _{PZH}	$\overline{OE}$	B or A	1	3.6	5.2	1	6.3	ns
t _{PZL}			1	3.7	5.4	1	6.4	
t _{PHZ}	$\overline{OE}$	B or A	2	4.4	5.8	2	6.3	ns
t _{PLZ}			1.5	3.3	4.7	1.5	5.2	



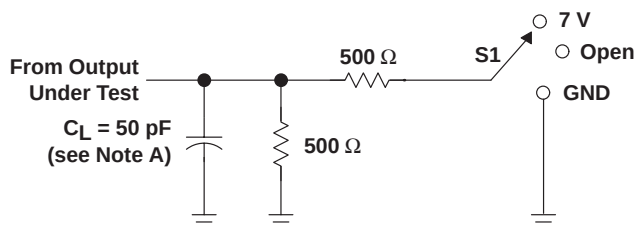
SN54ABTH16245, SN74ABTH16245

16-BIT BUS TRANSCEIVERS

WITH 3-STATE OUTPUTS

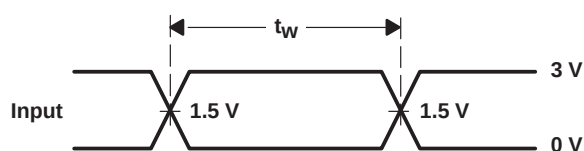
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PARAMETER MEASUREMENT INFORMATION

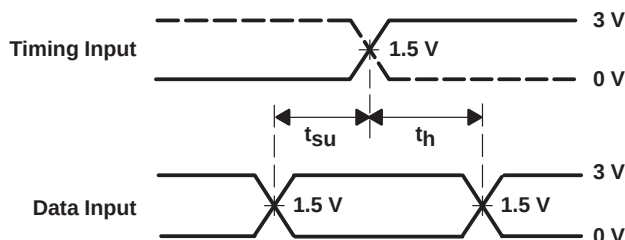


LOAD CIRCUIT

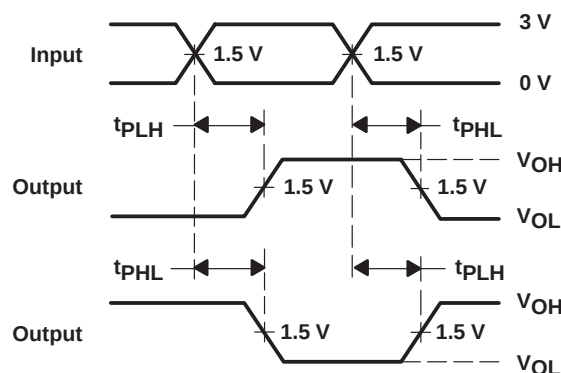
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



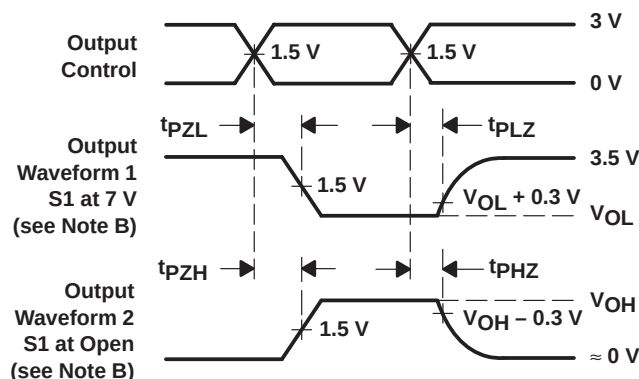
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ABTH16245DGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245	Samples
SN74ABTH16245DGVR	ACTIVE	TVSOP	DGV	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM245	Samples
SN74ABTH16245DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245	Samples
SN74ABTH16245DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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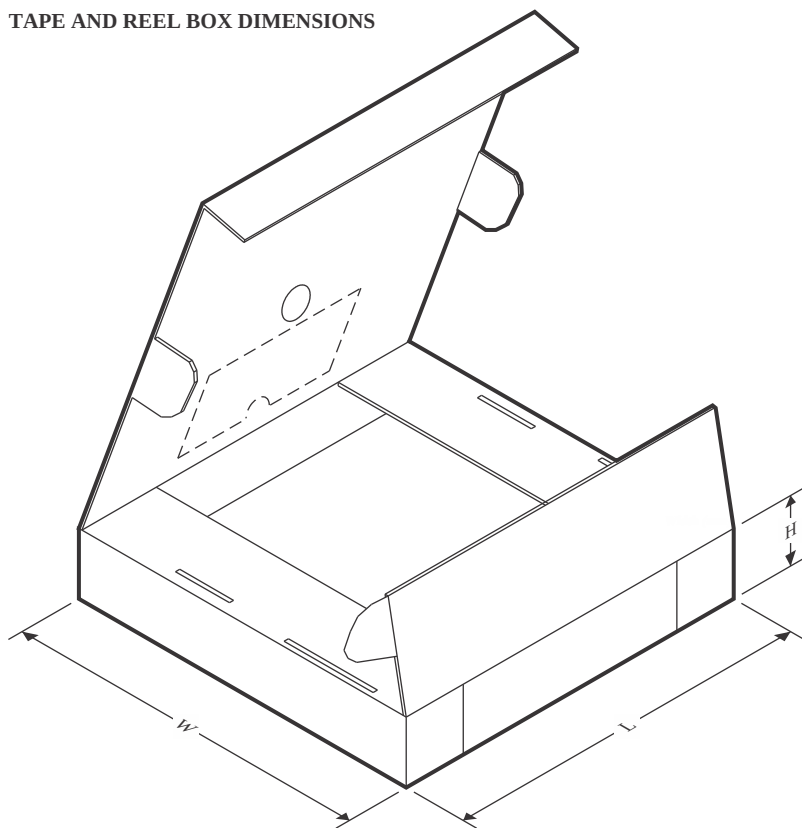
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTH16245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABTH16245DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74ABTH16245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABTH16245DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ABTH16245DGVR	TVSOP	DGV	48	2000	356.0	356.0	35.0
SN74ABTH16245DLR	SSOP	DL	48	1000	367.0	367.0	55.0

TUBE



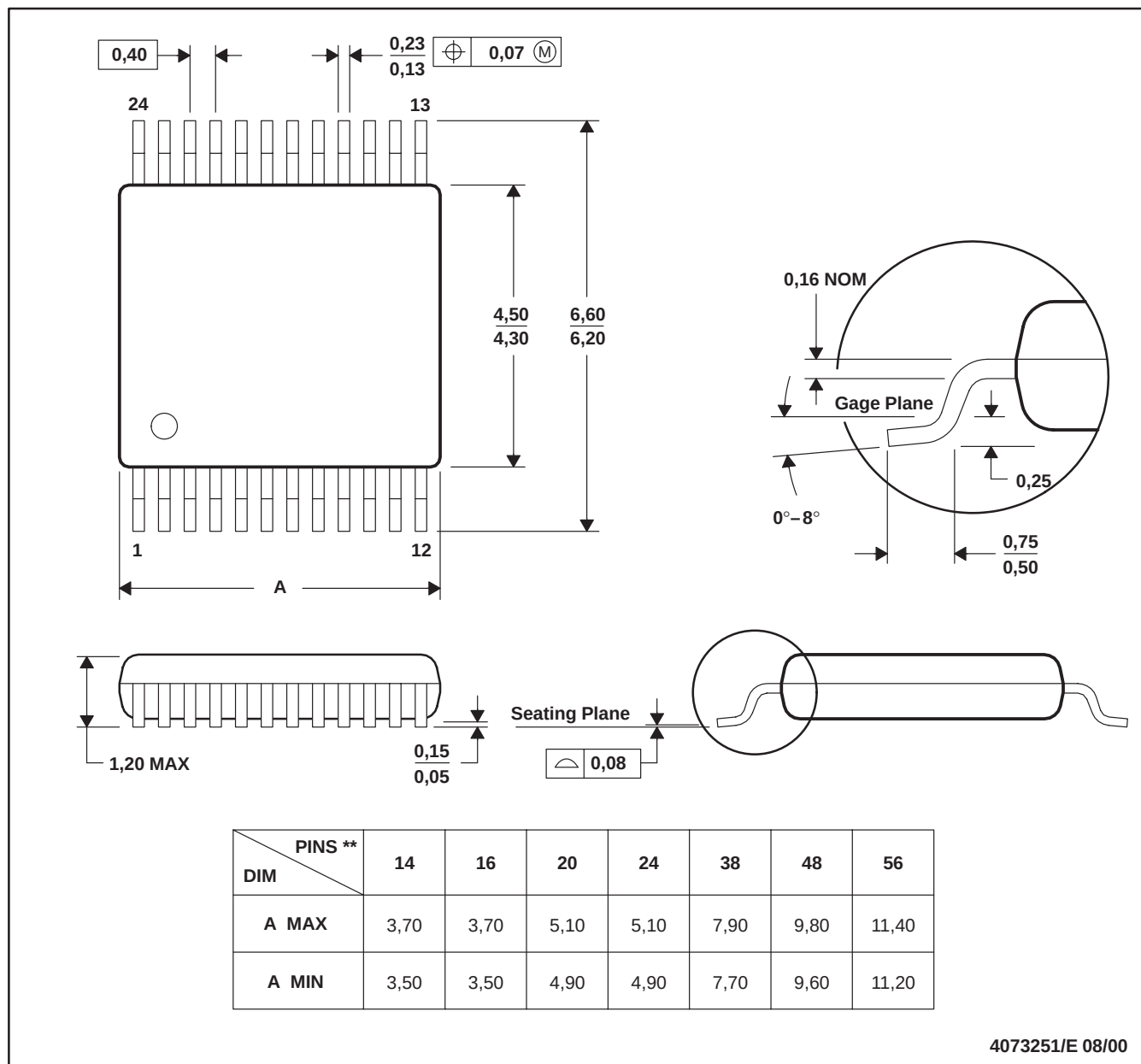
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ABTH16245DL	DL	SSOP	48	25	473.7	14.24	5110	7.87

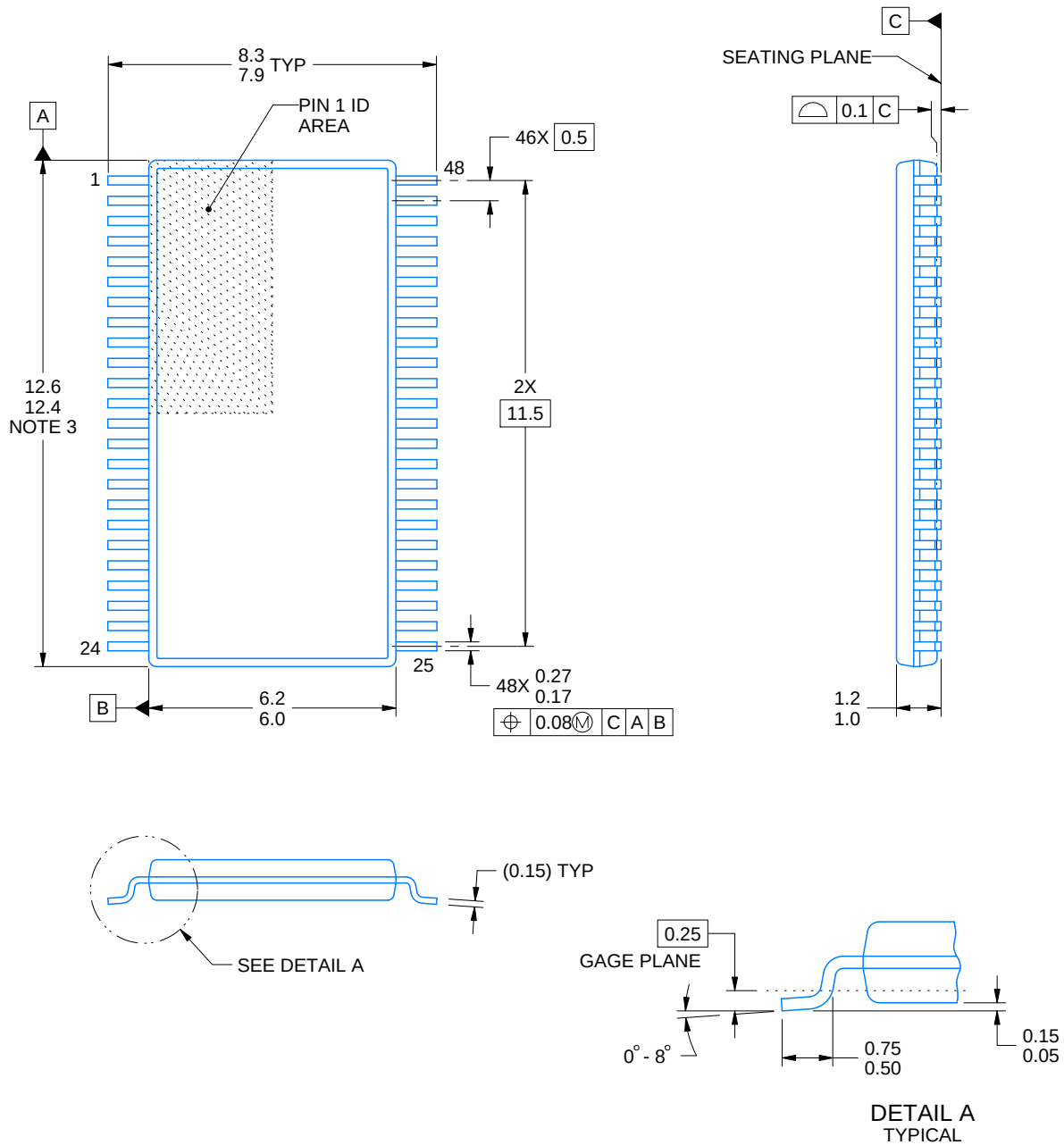
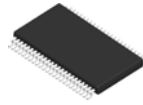
DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 - Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194



4214859/B 11/2020

NOTES:

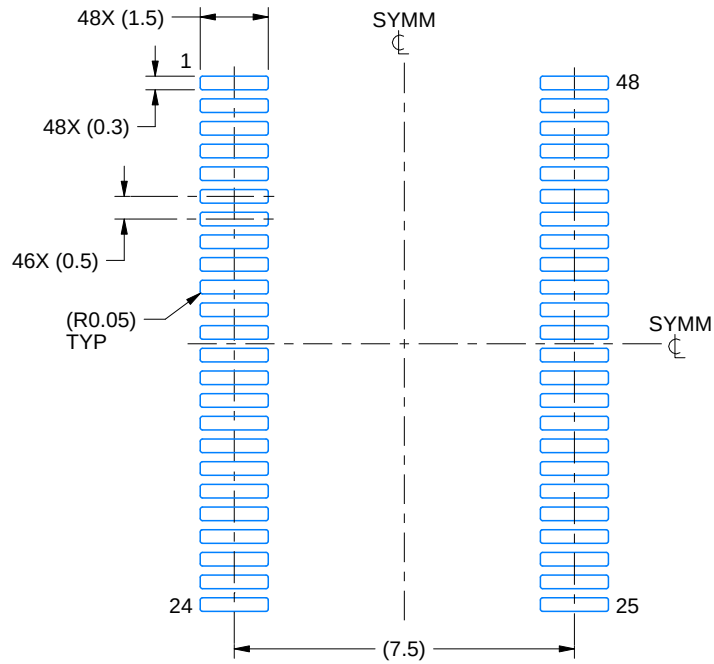
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

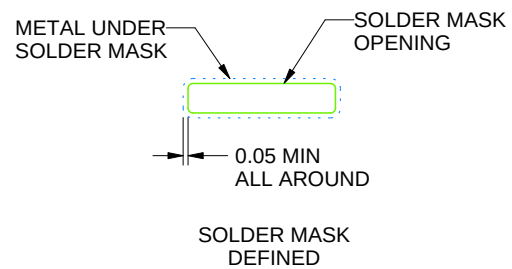
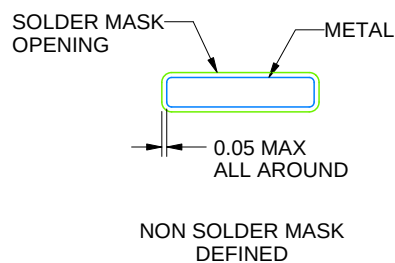
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

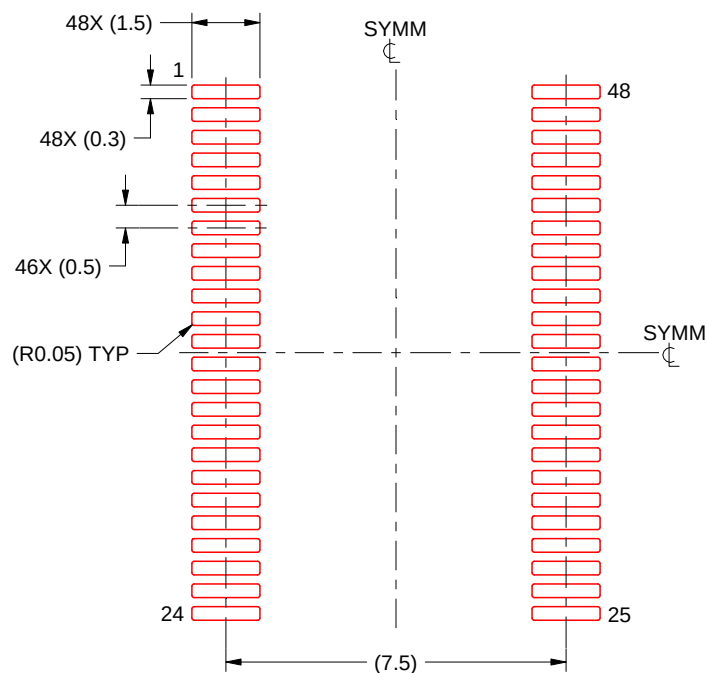
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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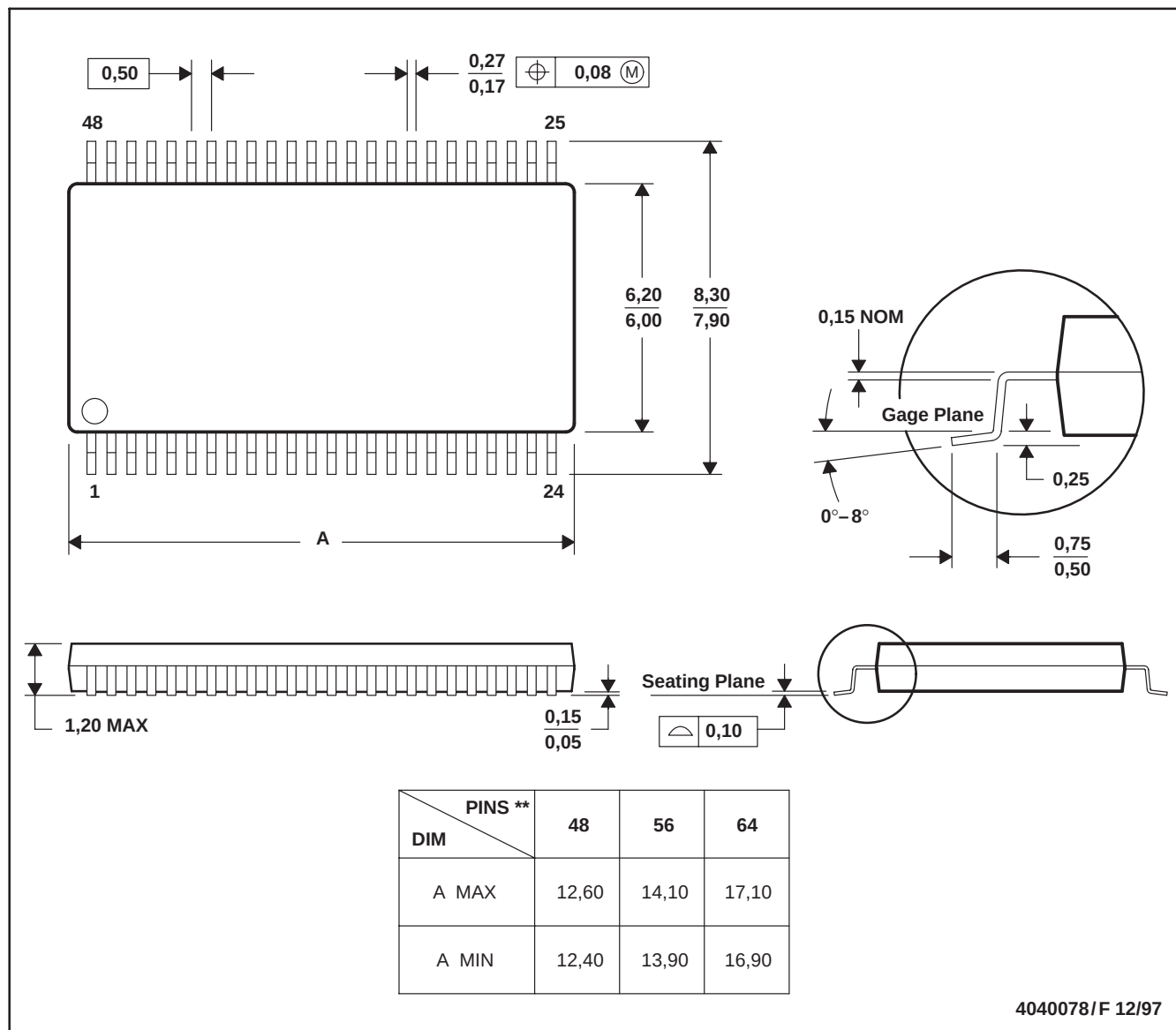
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

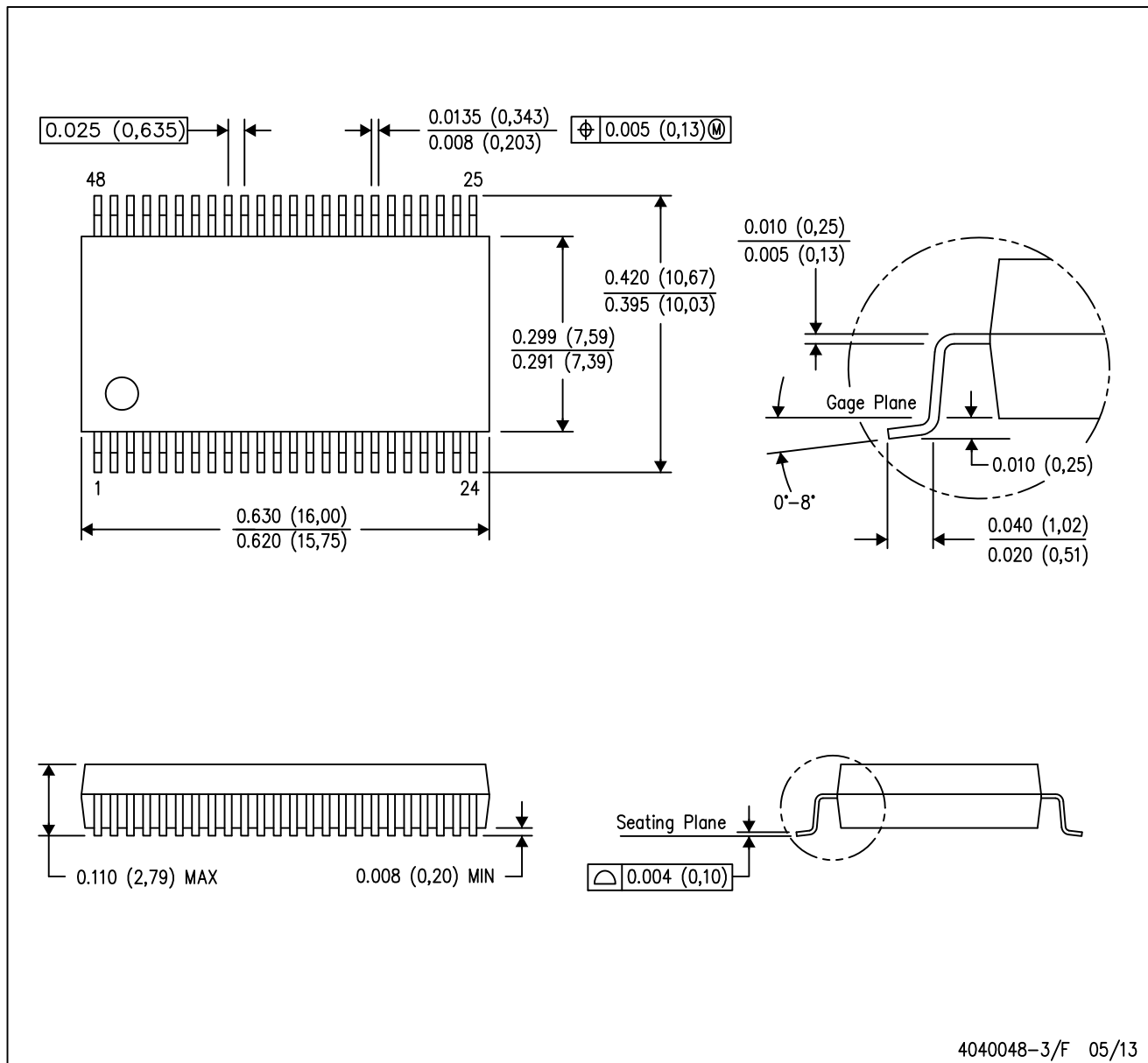
48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



4040048-3/F 05/13

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MO-118

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